

**Description**

This is 40V 22A N-channel mosfet in a SOP-8L plastic package.

Uses 2nd generation power trench mosfet technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching application.

**Applications**

- Power management switches
- DC/DC converter

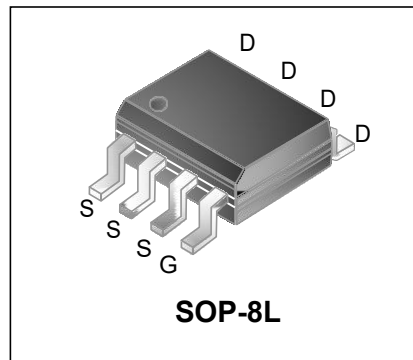
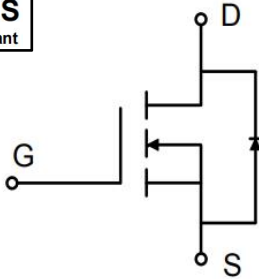
**Features**

- Green device available
- Low gate charge
- 100% EAS guaranteed

$V_{DSS}$	$R_{DS(on)}$	$I_D$
40 V	3.2 m $\Omega$	22 A

**Equivalent Circuit & Pinning**

RoHS  
compliant



**Absolute Maximum Ratings(Ta=25°C)**

Parameter		Symbol	Value	Unit
Drain-Source Voltage		<b>V<sub>DS</sub></b>	40	V
Gate-Source Voltage		<b>V<sub>GS</sub></b>	±20	V
Continuous Drain Current@10V <sup>1</sup>	T <sub>A</sub> =25°C	<b>I<sub>D</sub></b>	22	A
	T <sub>A</sub> =75°C		18	
Pulsed Drain Current <sup>2</sup>		<b>I<sub>DM</sub></b>	165	A
Single Pulse Avalanche Energy <sup>3</sup>		<b>EAS</b>	151	mJ
Avalanche Current		<b>I<sub>AS</sub></b>	55	A
Total Power Dissipation <sup>4</sup>	T <sub>A</sub> =25°C	<b>P<sub>D</sub></b>	22	W
Operating Junction and Storage Temperature Range		<b>T<sub>J</sub>, T<sub>STG</sub></b>	-55 to 150	°C

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	<b>R<sub>θJA</sub></b>	76	°C/W
Thermal Resistance from Junction-to-Case <sup>1</sup>	<b>R<sub>θJC</sub></b>	41	°C/W

**Electrical Characteristics(Ta=25°C)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Static Characteristics</b>							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	40	-	-	V	
Gate-Body Leakage current	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 40V, V_{GS} = 0V$	$T_J = 25^\circ C$	-	-	1	$\mu A$
			$T_J = 55^\circ C$	-	-	5	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.2	1.85	2.2	V	
Drain-Source on-Resistance <sup>2</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 15A$	-	2.6	3.2	m $\Omega$	
		$V_{GS} = 4.5V, I_D = 10A$	-	3.7	5.2		
Forward Transconductance <sup>2</sup>	$g_{fs}$	$V_{DS} = 5V, I_D = 20A$	-	76	-	S	
<b>Dynamic Characteristics</b>							
Input Capacitance	$C_{iss}$	$V_{DS} = 20V, V_{GS} = 0V, f = 1MHz$	-	2700	-	pF	
Output Capacitance	$C_{oss}$		-	1050	-		
Reverse Transfer Capacitance	$C_{rss}$		-	45	-		
<b>Switching Characteristics</b>							
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	-	0.7	-	$\Omega$	
Total Gate Charge	$Q_g$	$V_{GS} = 4.5V, V_{DS} = 20V, I_D = 20A$	-	22.5	-	nC	
Gate-Source Charge	$Q_{gs}$		-	7.6	-		
Gate-Drain Charge	$Q_{gd}$		-	5.4	-		
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = 10V, V_{DS} = 20V, R_G = 3\Omega, I_D = 20A$	-	9.8	-	nS	
Rise Time	$t_r$		-	5.2	-		
Turn-off Delay Time	$t_{d(off)}$		-	32	-		
Fall Time	$t_f$		-	6.6	-		
<b>Drain-Source Body Diode Characteristics</b>							
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	$I_S = 1A, V_{GS} = 0V$	-	-	1	V	
Continuous Source Current <sup>1,5</sup>	$I_S$	$V_G = V_D = 0V, \text{ Force Current}$	-	-	22	A	

**Notes:**

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is  $V_{DD} = 25V, V_{GS} = 10V, L = 0.1mH, I_{AS} = 55A$
- 4.The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications , should be limited by total power dissipation

Electrical Characteristic Curve

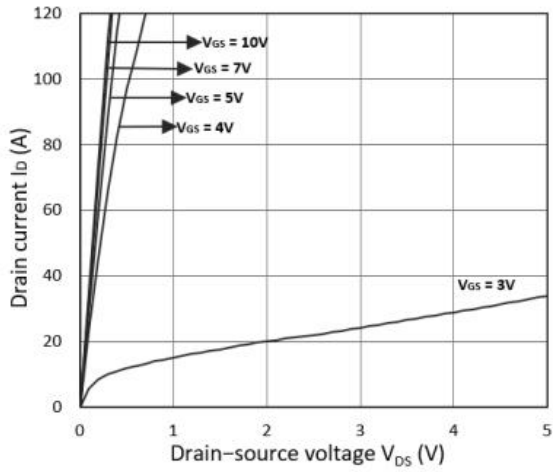


Figure 1. Output Characteristics

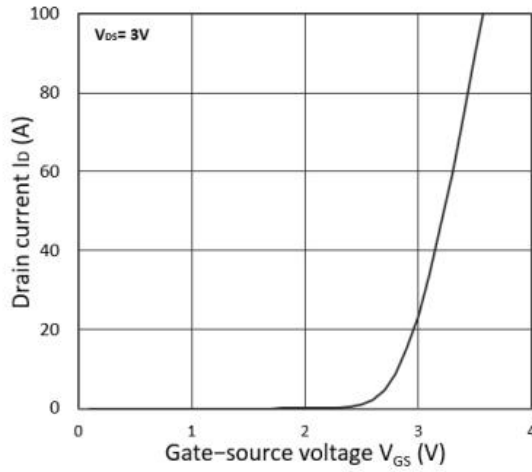


Figure 2. Transfer Characteristics

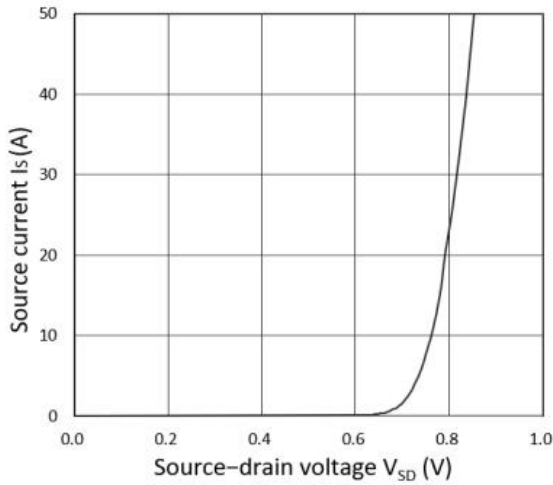


Figure 3. Forward Characteristics of Reverse

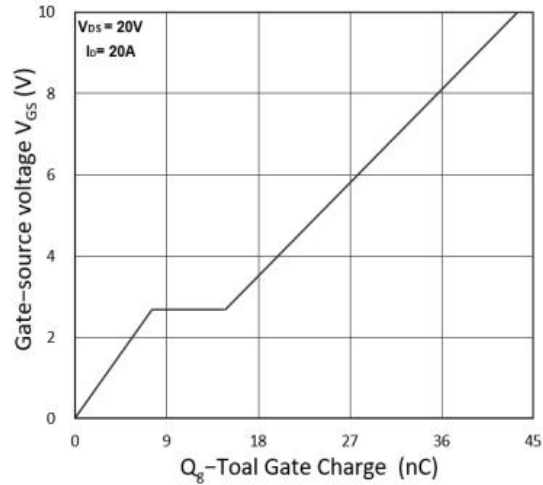


Figure 4. Gate Charge Characteristics

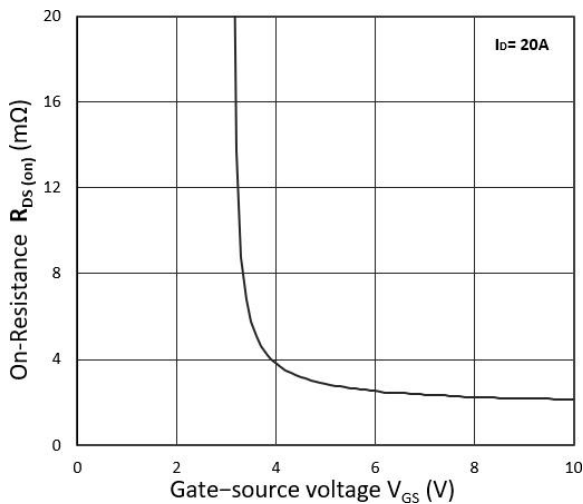


Figure 5.  $R_{DS(on)}$  vs.  $V_{GS}$

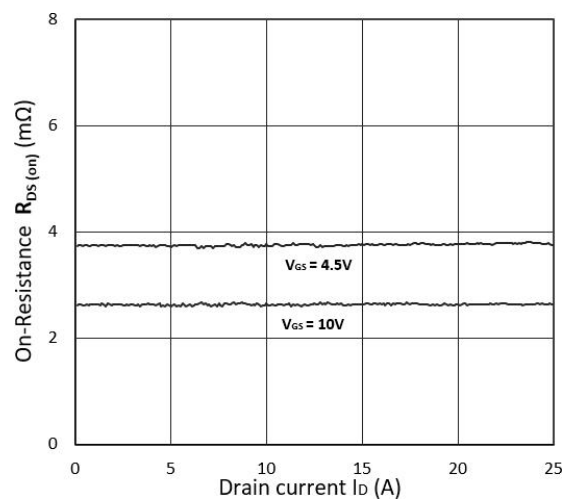


Figure 6.  $R_{DS(on)}$  vs.  $I_D$

Electrical Characteristic Curve

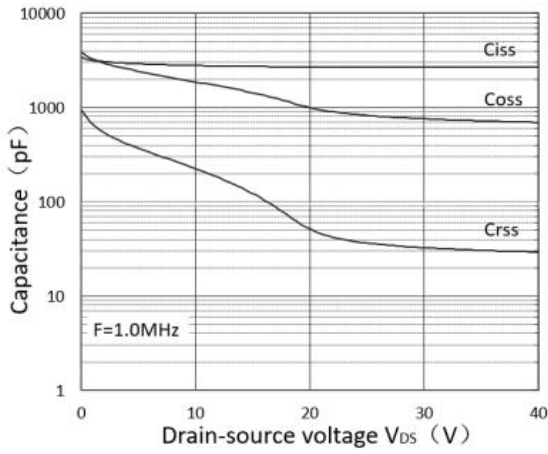


Figure 7. Capacitance Characteristics

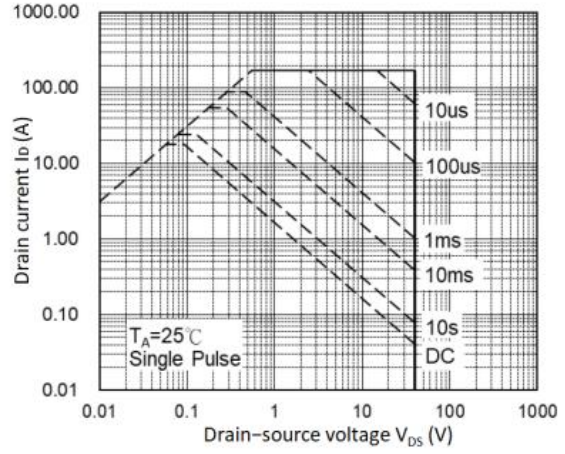


Figure 8. Safe Operating Area

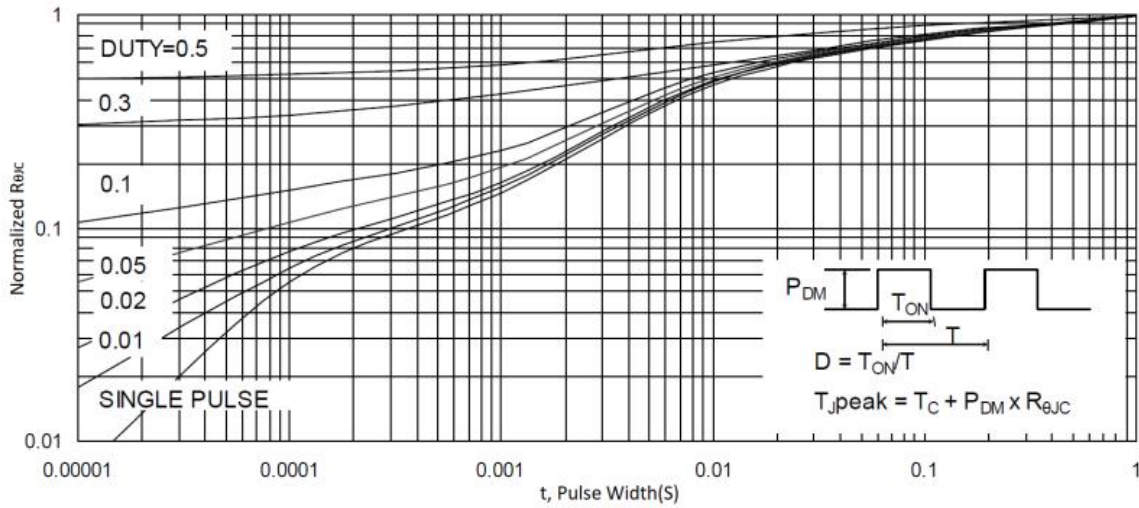


Figure 9. Normalized Maximum Transient Thermal Impedance

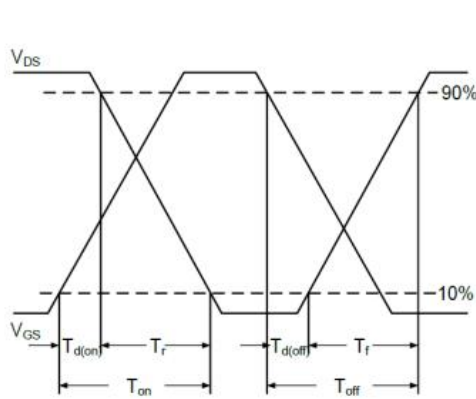


Figure 10. Switching Time Waveform

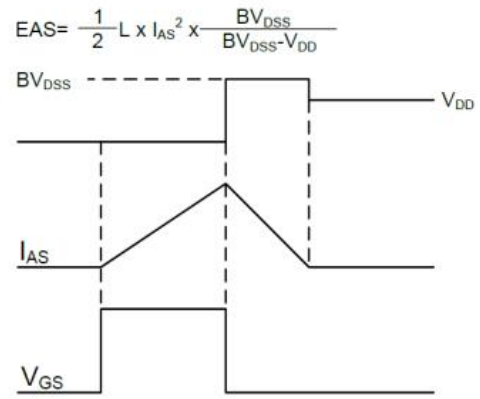
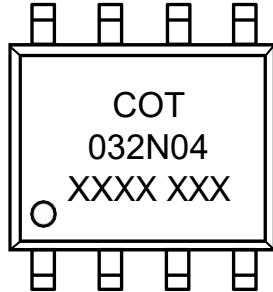


Figure 11. Unclamped Inductive Switching Waveform

Marking Instructions



Note:

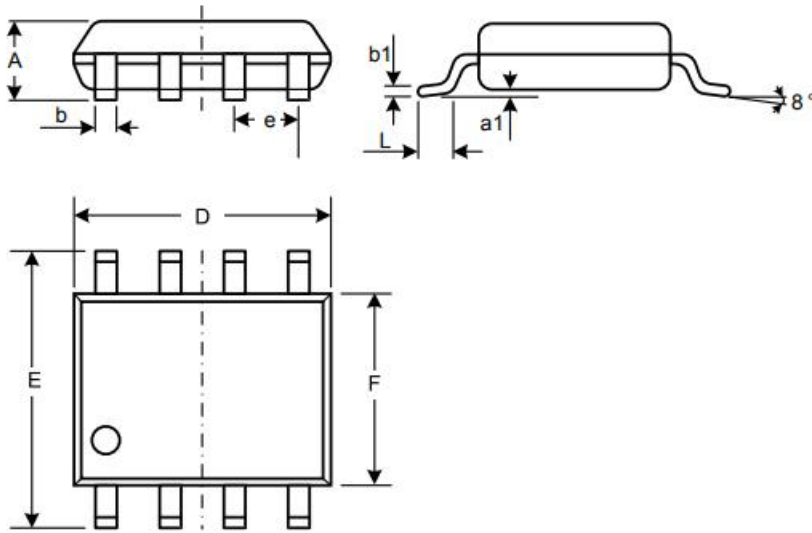
- COT: Company Logo
- 032N04: Product Type
- XXXX XXX: Date code

Ordering Information

Part	Package	Marking	Packing method
CT032N04SC	SOP-8L	032N04	Tape and Reel

Mechanical Dimensions for SOP-8L

COMMON DIMENSIONS



SYMBOL	MM	
	MIN	MAX
A	1.23	1.75
a1	0.05	0.25
b	0.31	0.51
b1	0.16	0.25
D	4.70	5.15
E	5.75	6.25
e	1.07	1.47
F	3.70	4.10
L	0.4	1.27